14A, 600V SUPER JUNCTION MOS POWER TRANSISTOR

DESCRIPTION

SVS60R240FJD(D)D4 is an N-channel enhancement mode high voltage power MOSFETs produced using Silan's super junction MOS technology. It achieves low conduction loss and switching losses. It leads the design engineers to their power converters with high efficiency, high power density, and superior thermal behavior.

Furthermore, it's universal applicable, i.e., suitable for hard and soft switching topologies.

FEATURES

- 14A, 600V, $R_{DS(on)(typ.)}$ =0.20 Ω @ V_{GS} =10V
- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- High peak current capability
- 100% avalanche tested
- Pb-free lead plating
- · RoHS compliant

1. Gate 2. Drain 3. Source 123 TO-252-2L TO-220FJD-3L

KEY PERFORMANCE PARAMETERS

Characteristics	Ratings	Unit
V _{DS} @T _J .max	650	V
V _{GS(th)}	2.5~4.5	V
R _{DS(on)} , max.	0.24	Ω
I _{D.pulse}	56	А
Q _{g.typ.}	28	nC

ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVS60R240FJDD4	TO-220FJD-3L	60R240D4	Halogen free	Tube
SVS60R240DD4TR	TO-252-2L	60R240D4	Halogen free	Tape & Reel

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ABSOLUTE MAXIMUM RATINGS (UNLESS OTHERWISE NOTED, T_J=25°C)

Observatoriation	Ormali al	Test conditions	Ratings			Unit
Characteristics	Symbol Test conditions	Min.	Тур.	Max.	Onit	
Gate-source Voltage (Static)	V_{GS}		-20		20	V
Gate-source Voltage (Dynamic)	V_{GS}	AC(f>1Hz)	-30		30	V
Drain Current	I _D	T _C =25°C	1		14	Α
Diam Current	ID	T _C =100°C	-		8.8	Α
Drain Current Pulsed (Note 1)	I_{DM}	T _C =25°C	1		56	Α
Power Dissipation (TO-220FJD-3L) (Note 2)	P_{D}	T _C =25°C	-		24.5	W
Power Dissipation (TO-252-2L) (Note 2)	P _D	T _C =25°C	1		119	W
Single Pulsed Avalanche Energy	E _{AS}	L=79mH, V_{DD} =100V, R_{G} =25 Ω , starting temperature T_{J} =25 $^{\circ}$ C	1		311	mJ
Single Pulsed Current	I_{AS}				2.6	Α
Reverse Diode dv/dt	dv/dt	$V_{DS}=0~400V, I_{SD}<=I_{S},$ $T_{J}=25^{\circ}C$			15	V/ns
MOS dv/dt Ruggedness	dv/dt	V _{DS} =0~480V			50	V/ns
Operation Junction Temperature Range	TJ		-55		150	°C
Storage Temperature Range	T _{stg}		-55		150	°C
Continuous Diode Forward Current	Is	T _C =25°C, integral reverse P-N	-		14	А
Diode Pulse Current	I _S , _{pulse}	junction diode in the MOSFET			56	Α
Maximum Diode Commutation Speed	di/dt	$V_{DS}=0~400V, I_{SD}<=I_{S},$ $T_{J}=25^{\circ}C$			500	A/µs

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THERMAL CHARACTERISTICS

Table1. TO-220FJD-3L (SVS60R240FJDD4)

Characteristics	Symbol	Test conditions	Ratings			Unit
			Min.	Тур.	Max.	Oilit
Thermal Resistance,	$R_{ hetaJC}$				5.1	°C/W
Junction-case, Bottom						
Thermal Resistance,	$R_{ hetaJA}$				60.5	0000
Junction-ambient					62.5	°C/W
Soldering Temperature (in line)	T _{sold}	15 ⁺² ₋₀ sec, 1time			260	°C

Table 2. TO-252-2L (SVS60R240DD4)

Characteristics	Symbol	Test conditions Min.		Ratings		
	Syllibol		Min.	Тур.	Max.	Unit
Thermal Resistance,	R _{θJC}				1.05	°C/W
Junction-case, Bottom						
Thermal Resistance,	$R_{ heta JA}$				62.0	°C/W
Junction-ambient					02.0	-0/00
Soldering Temperature(SMD)	T _{sold}	Reflow soldering: 10±1sec, 3times			260	°C

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ELECTRICAL CHARACTERISTICS (UNLESS OTHERWISE NOTED,T,=25°C)

Static characteristics

Characteristics	Symbol	Test conditions	Ratings			Unit
	Syllibol	rest conditions	Min.	Тур.	Max.	Offic
Drain-source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250µA	600			V
Drain-source Leakage Current	I	V _{DS} =600V, V _{GS} =0V, T _J =25°C			1.0	
	I _{DSS}	V _{DS} =600V, V _{GS} =0V, T _J =125°C		1.0		μΑ
Gate-source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}$, $I_{D}=250\mu A$	2.5		4.5	V
Static Drain-source	D	V _{GS} =10V, I _D =7A, T _J =25°C		0.20	0.24	0
On State Resistance	$R_{DS(on)}$	V _{GS} =10V, I _D =7A, T _J =150°C		0.48		Ω
Gate Resistance	R _G	f=1MHz		1.2		Ω

Dynamic characteristics

Characteristics	Compleal	Symbol Test conditions	Ratings			l lmi4
	Symbol Test conditions	Min.	Тур.	Max.	Unit	
Input Capacitance	C _{iss}			923		
Output Capacitance	Coss	f=1MHz, V _{GS} =0V, V _{DS} =100V		44		pF
Reverse Transfer Capacitance	C _{rss}			2.5		ı
Turn-on Delay Time	t _{d(on)}	V_{DD} =300V, V_{GS} =10V, R_{G} =24 Ω , I_{D} =14A (Notes 3, 4)		17		
Turn-on Rise Time	t _r			45		l
Turn-off Delay Time	t _{d(off)}			60		ns
Turn-off Fall Time	t _f			31		
Total Gate Charge	Qg			28		
Gate-source Charge	Q _{gs}	V _{DD} =480V, V _{GS} =10V, I _D =14A		7.7		nC
Gate-drain Charge	Q_{gd}	(Notes 3, 4)		14		
Gate-plateau Voltage	V _{plateau}			7.2		V

Reverse diode characteristics

Characteristics	Symbol	Test conditions	Ratings			Unit
	Oymbol Test conditio	rest conditions	Min.	Тур.	Max.	Offic
Diode Forward Voltage	V_{SD}	I _S =14A, V _{GS} =0V			1.4	V
Reverse Recovery Time	Trr	1 444 \/ 0\/ \/ 50\/		308		ns
Reverse Recovery Charge	Qrr	I _S =14A, V _{GS} =0V, V _R =50V, dI _F /dt=100A/μs (Note 3)		4.3		μC
Reverse Recovery Peak Current	I _{rrm}			27		Α

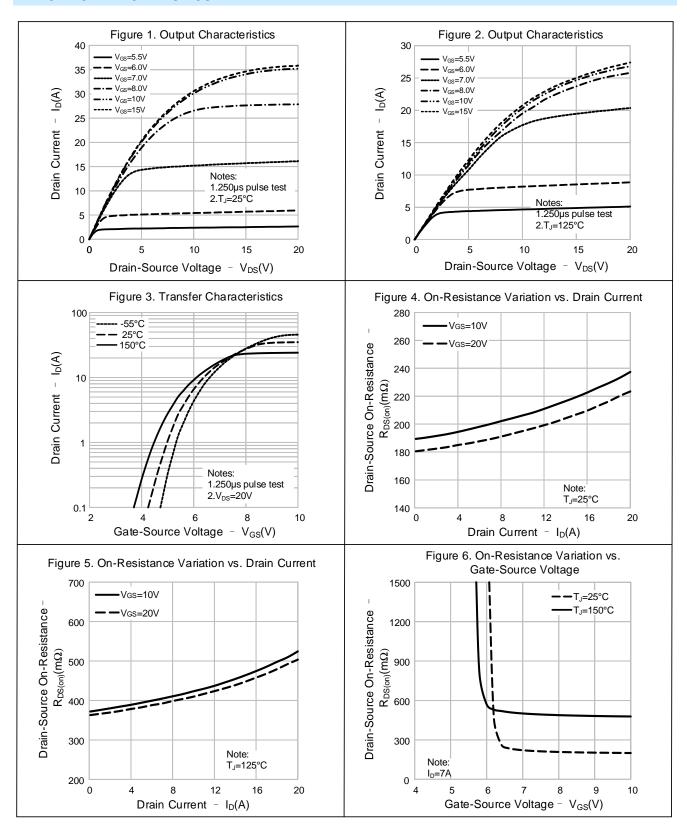
Notes:

- Pulse time 5µs;
- 2. The dissipation power will change with temperature, derating above 25°C:0.2W/°C (TO-220FJD-3L)/0.95W/°C(TO-252-2L);
- 3. Pulse Test: Pulse width ≤300µs, Duty cycle≤2%;
- 4. Essentially independent of operating temperature.

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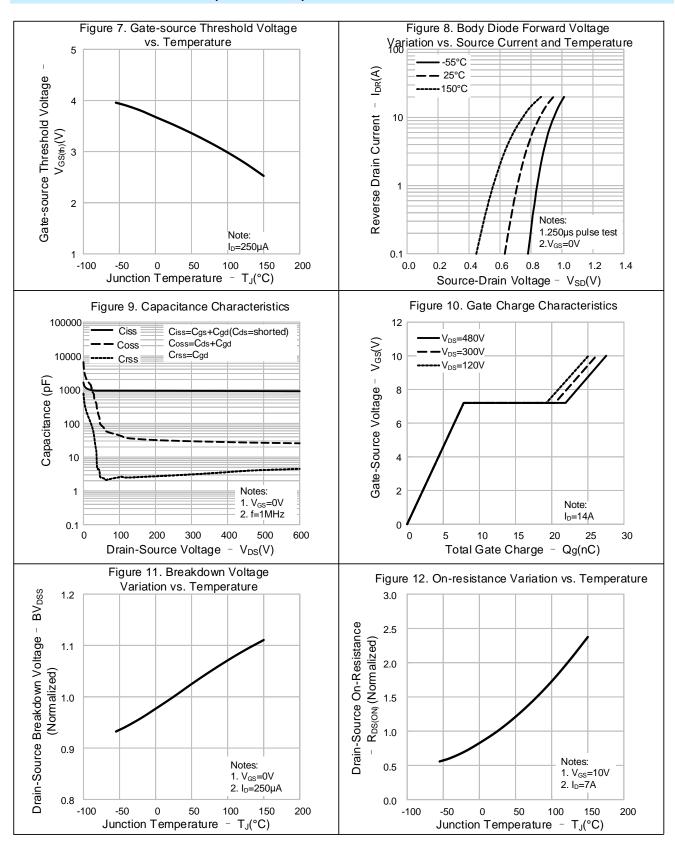


TYPICAL CHARACTERISTICS



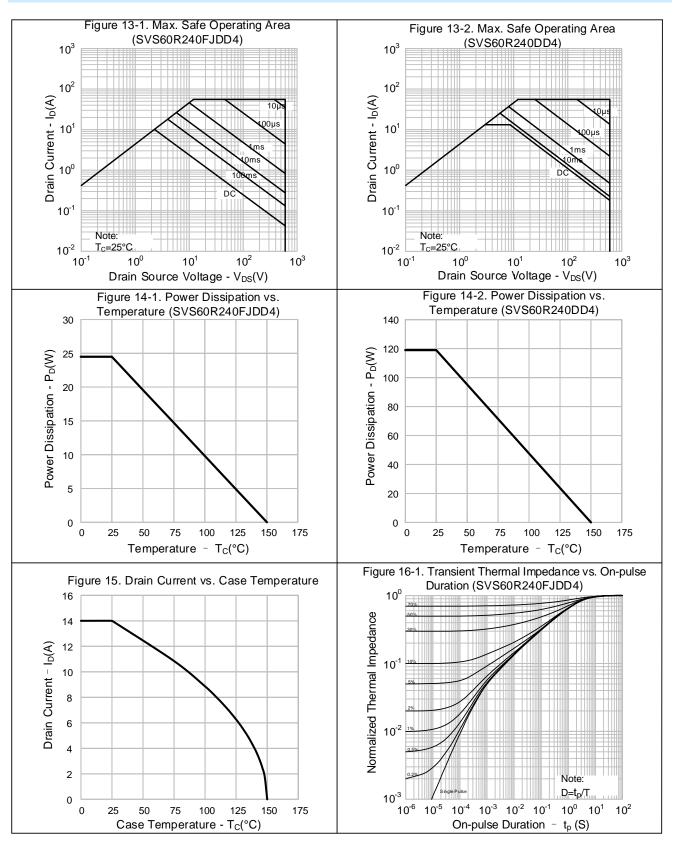


TYPICAL CHARACTERISTICS (CONTINUED)



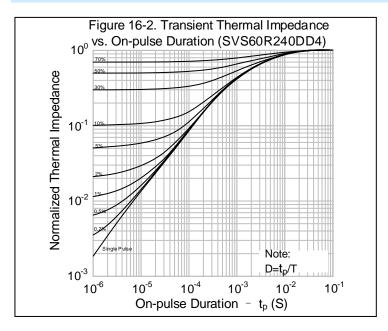


TYPICAL CHARACTERISTICS (CONTINUED)





TYPICAL CHARACTERISTICS (CONTINUED)

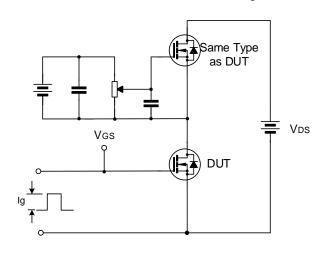


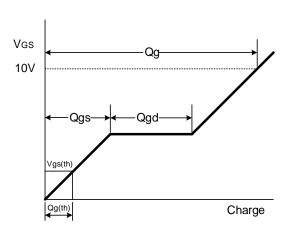
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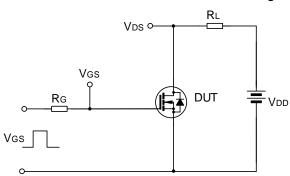
TYPICAL TEST CIRCUIT

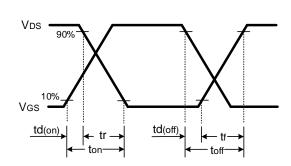
Gate Charge Test Circuit & Waveform



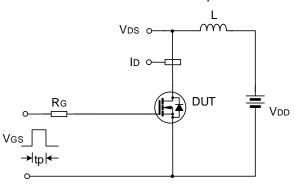


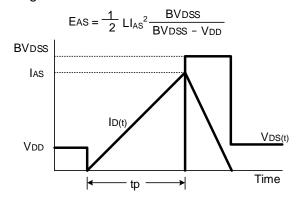
Resistive Switching Test Circuit & Waveform





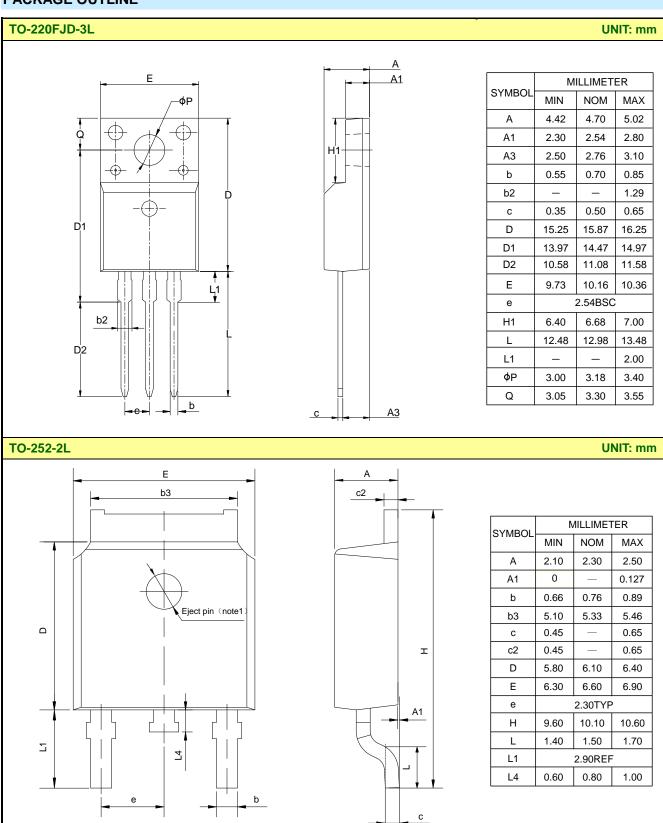
Unclamped Inductive Switching Test Circuit & Waveform







PACKAGE OUTLINE



NOTE1: There are two conditions for this position:has an eject pin or has no eject pin.

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MOS DEVICES OPERATE NOTES:

Electrostatic charges may exist in many things. Please take following preventive measures to prevent effectively the MOS electric circuit as a result of the damage which is caused by discharge:

- The operator must put on wrist strap which should be earthed to against electrostatic.
- Equipment cases should be earthed.
- All tools used during assembly, including soldering tools and solder baths, must be earthed.
- MOS devices should be packed in antistatic/conductive containers for transportation.

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1.0 Rev.: Revision History:

First release

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